



Taichung ICSS2022

International Conference on Smart Sensors
October 22-23, 2022 | TAICHUNG, TAIWAN

Hold on October 22-23, 2022 at National Chun Hsing University Taichung, Taiwan. The conference is a joint event of 27th Symposium of Association of Chemical Sensors in Taiwan and 25th Nano Engineering and Microsystem Technology Conference. The ICSS is a premier conference in Taiwan focusing on the promotion of advanced research and industrial collaboration. The ICSS 2022 is expected to attract over 500 attendees and 40 industrial booths and will provide an excellent platform for the academics and industrial companies.

List of Topics

- Sensing Materials, Processing, and Fabrications
- Physical Sensors and Microsystems
- Chemical Sensors and Microsystems
- Optical and Acoustic Sensors
- Biosensors including in-vitro Diagnoses
- Wearable and in-vivo Medical Microsystems
- RF MEMS and Resonators
- Microfluidic Technologies
- Actuators and Microsystems
- Power and Energy Management of Sensor Systems
- Sensors Systems: Interface and Data Processing
- Applications of Sensors and Actuators Systems: IoT and Network
- Others

SUBMISSION GUIDELINES

All papers must be original and not Simultaneously submitted to another journal or conference.

<https://icss2022.conf.tw/site/mypage.aspx?pid=13&lang=en&sid=1447>



IMPORTANT DATES

- Registration Open
Thursday, May 12, 2022
- Registration Open (Early bird)
Friday, September 23, 2022
- Paper Submission Open
Tuesday, May 24, 2022
- Paper Submission Deadline
Friday, August 26, 2022
- Author Notification Date:
Friday, September 16, 2022
- Author Registration/Final Paper Submission Deadline
Friday, September 23, 2022
(Tentative date)

ORGANIZERS

Chair/Co-Chair

Prof. Ming-Tzer Lin, Institute of Precision Engineering, National Chung Hsing University
Prof. Chi-Chang Lin, Department of Chemical and Materials Engineering, Tung Hai University

Technical Program

Distinguished Prof. Hishang Yang, Institute of Precision Engineering, National Chung Hsing University
Distinguished Prof. Gu Yesong, Department of Chemical Engineering and Materials Engineering, Tung Hai University

Organizer



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